

(0,80mm) .0315" **QTE SERIES**

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTE

FILE NO. E111594

Insulator Material: Liquid Crystal Polymer

Terminal Material: Phosphor Bronze

Plating: Au or Sn over 50μ" (1,27μm) Ni Current Rating: Contacts: 1.3A @ 95°C Ground Plane: 10.1A @ 95°C Operating Temp Range: -55°C to +125°C Voltage Rating:

225 VAC mated with QSE & 5mm Stack Height Max Cycles: 100 Unmating Force (-RT1 option):

-RT1 option increases unmating force up to 50% RoHS Compliant:

Processing:

Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (020-060) (0,15mm) .006" max (080) **Board Stacking:**

For applications requiring more than two connectors per board or 4 banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30u" (0.76um) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount
- 100 positions per row
- · Guide Posts, Screw Down & Friction Lock

Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.



Cable Mates: EQCD, EQSD EQDP, EQRF (See Application Specific note)



5mm Stack Height	Туре	Rated @ 3dB Insertion Loss
Single-Ended Signaling	-D	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?QTE or contact sig@samtec.com

ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

- SAMTEC • E.L.P.™ plating
- option (-C)
- Retention pin option

Protocols

8 8

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XAUI PCI Express® SATA

MGT (Rocket 1/0) Infiniband

Download app notes at www.samtec.com/appnote Contact SIG @ samtec.com for questions on protocols 8

LEAD PINS PER ROW **PLATING OTHER** NO. OF PAIRS STYLE OPTION **OPTION**

from

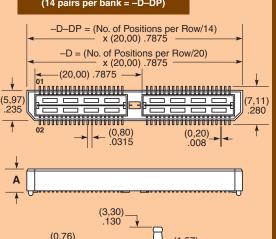
020, -040, -060, -080 (40 total pins per bank = -D)

014, -028, -042, -056(14 pairs per bank = -D-DP)

.030

(0,89)

.035 DÍA



Specify **LEAD** STYLE = Gold Flash on Signal Pins and chart Ground Plane, Matte Tin on tails

= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C* = Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ' (3,81µm) Ni on Śignal Pins in contact area 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area, Matte Tin over 50µ' (1,27µm) min Ni on all solder tails

.025

LEAD WITH QSE' (4,27) .168 (5,00) .197 -01 (7,26) .286 (8,00) .315 -02 (11,00) .433 (10,27) .404 -03 (16,00) .630 (15.25)-04.600 (19,00) .748 18,26) -05.718 (24,24) .954 (25,00) .984 -07

*Processing conditions

will affect mated height.

OTE

−D = Single-Ended -D-DP Differential Pair (-01 only)

HEIGHT

-K = (7,00mm) .275" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging (N/A on 56 & 80 positions or -05 & -07 lead

> style) -RT1

= Retention Option (-01 Lead Style only) (N/A on 56 & 80 positions or -L (latch) option)

= Latching Option (N/A on 42, 56, 60 & 80 positions or -RT1 option)

Due to technical progress, all designs, specifications and components are subject to change without notice.

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